

Standard Avalanche SMD Rectifier


DO-214AC (SMA)

FEATURES

- Low profile package
- Ideal for automated placement
- Controlled avalanche characteristics
- Glass passivated pallet chip junction
- Low reverse current
- High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, automotive, and telecommunication.

MECHANICAL DATA

Case: DO-214AC (SMA)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-E3 - RoHS-compliant, commercial grade
Base P/NHE3 - RoHS-compliant, AEC-Q101 qualified

Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 2 whisker test, HE3 suffix meets JESD 201 class 2 whisker test

Note

- BYG10Y for commercial grade only

Polarity: Color band denotes the cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	1.5 A
V_{RRM}	200 V, 400 V, 600 V, 800 V, 1000 V, 1600 V
I_{FSM}	30 A
I_R	1.0 μ A
V_F	1.15 V
E_R	20 mJ
T_J max.	150 °C
Package	DO-214AC (SMA)
Diode variations	Single die

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)								
PARAMETER	SYMBOL	BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	UNIT
Device marking code		BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	1600	V
Average forward current	$I_{F(AV)}$	1.5						A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	30						A
Pulse energy in avalanche mode, non repetitive (inductive load switch off) $I_{(BR)R} = 1\text{ A}$, $T_J = 25\text{ °C}$ (for BYG10D thru BYG10M) $I_{(BR)R} = 0.4\text{ A}$, $T_J = 25\text{ °C}$ (for BYG10Y)	E_R	20						mJ
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150						°C



ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)										
PARAMETER	TEST CONDITIONS		SYMBOL	BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	UNIT
Maximum instantaneous forward voltage ⁽¹⁾	I _F = 1 A	T _J = 25 °C	V _F	1.1						V
	I _F = 1.5 A			1.15						
Maximum DC reverse current	V _R = V _{RRM}	T _J = 25 °C	I _R	1						μA
		T _J = 100 °C		10						
Maximum reverse recovery time	I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A		t _{rr}	4						μs

Note

⁽¹⁾ Pulse test: 300 μs pulse width, 1 % duty cycle

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	BYG10D	BYG10G	BYG10J	BYG10K	BYG10M	BYG10Y	UNIT
Typical thermal resistance, junction to lead	R _{θJL}	25						°C/W
Typical thermal resistance, junction to ambient	R _{θJA} ⁽¹⁾	150						°C/W
	R _{θJA} ⁽²⁾	125						
	R _{θJA} ⁽³⁾	100						

Notes

- ⁽¹⁾ Mounted on epoxy-glass hard tissue
⁽²⁾ Mounted on epoxy-glass hard tissue, 50 mm² 35 μm Cu
⁽³⁾ Mounted on Al-oxide-ceramic (Al_2O_3), 50 mm² 35 μm Cu

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
BYG10D-E3/TR	0.064	TR	1800	7" diameter plastic tape and reel
BYG10D-E3/TR3	0.064	TR3	7500	13" diameter plastic tape and reel
BYG10DHE3/TR ⁽¹⁾	0.064	TR	1800	7" diameter plastic tape and reel
BYG10DHE3/TR3 ⁽¹⁾	0.064	TR3	7500	13" diameter plastic tape and reel

Note

⁽¹⁾ AEC-Q101 qualified

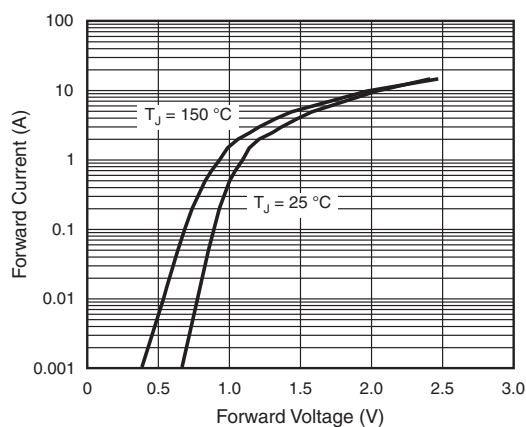
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Fig. 1 - Forward Current vs. Forward Voltage

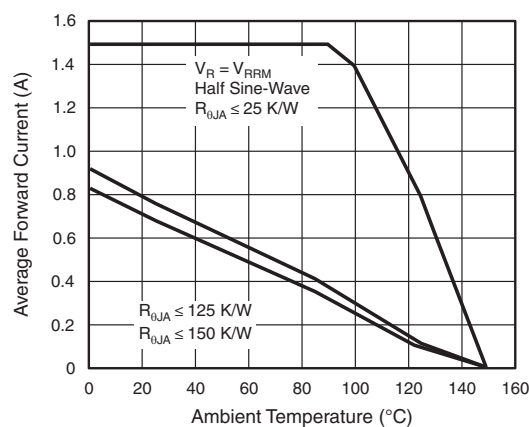


Fig. 2 - Max. Average Forward Current vs. Ambient Temperature

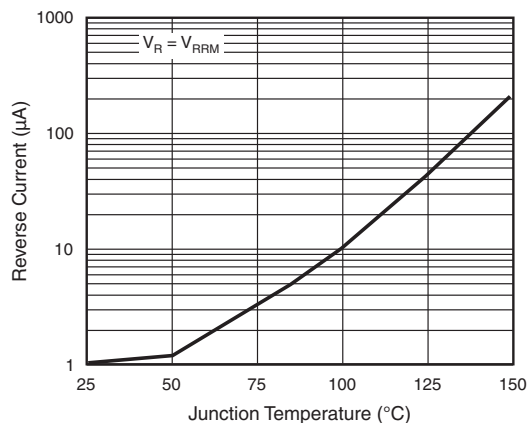


Fig. 3 - Reverse Current vs. Junction Temperature

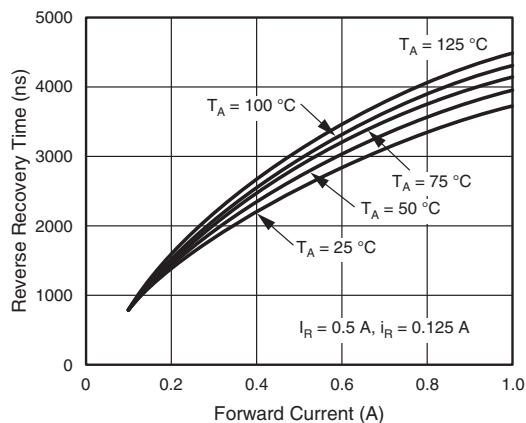


Fig. 6 - Reverse Recovery Time vs. Forward Current

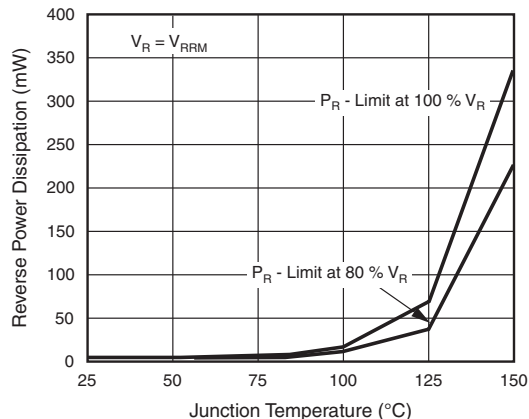


Fig. 4 - Max. Reverse Power Dissipation vs. Junction Temperature

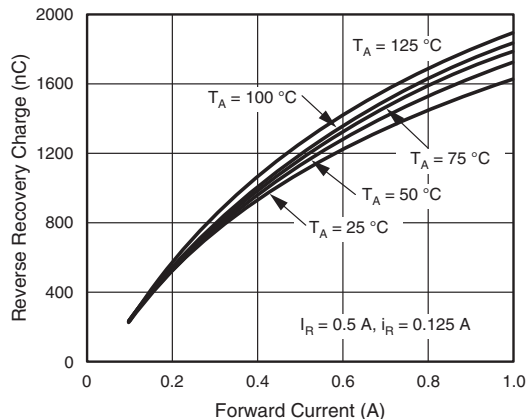


Fig. 7 - Reverse Recovery Charge vs. Forward Current

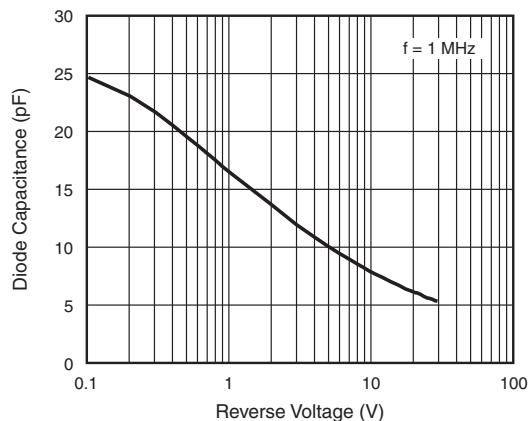
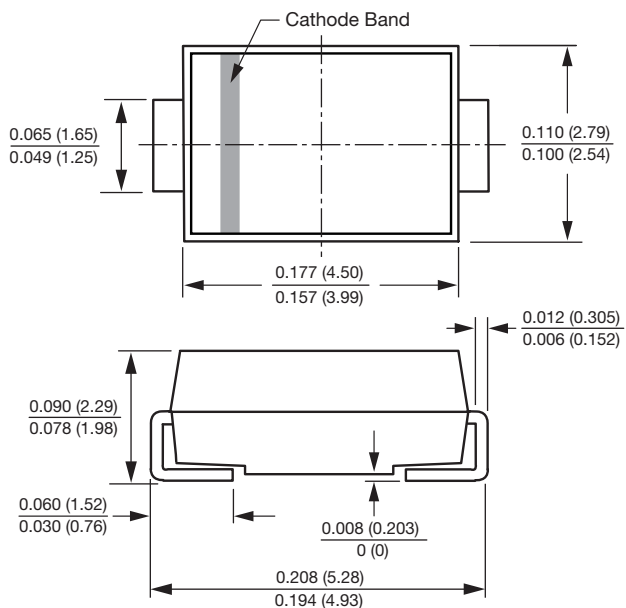


Fig. 5 - Diode Capacitance vs. Reverse Voltage

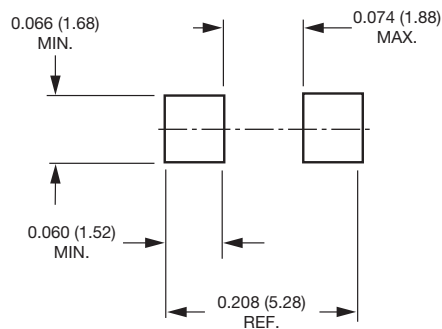


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

DO-214AC (SMA)



Mounting Pad Layout





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